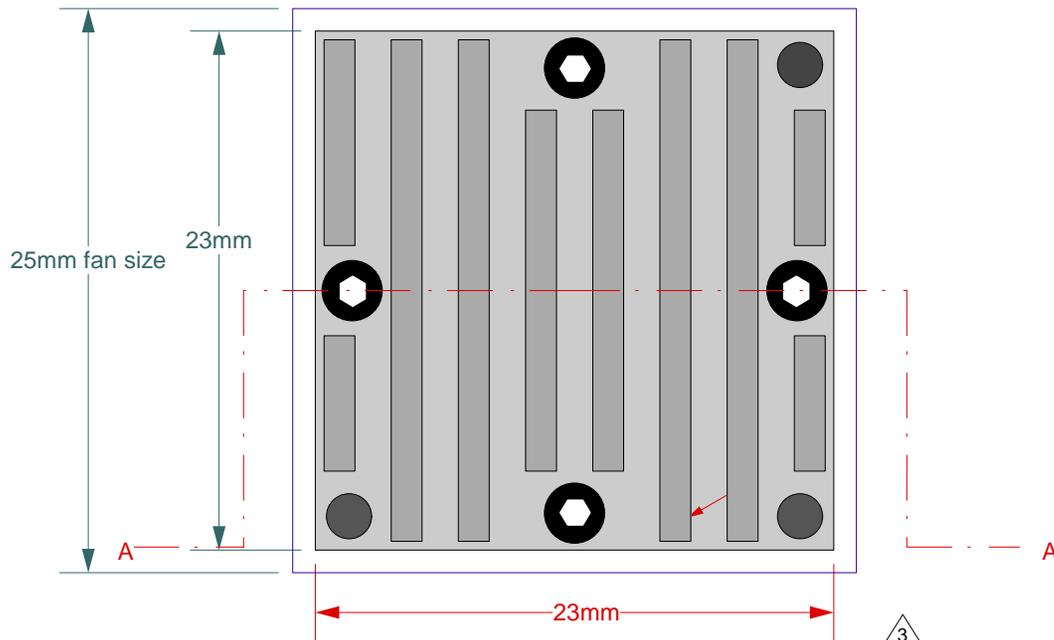


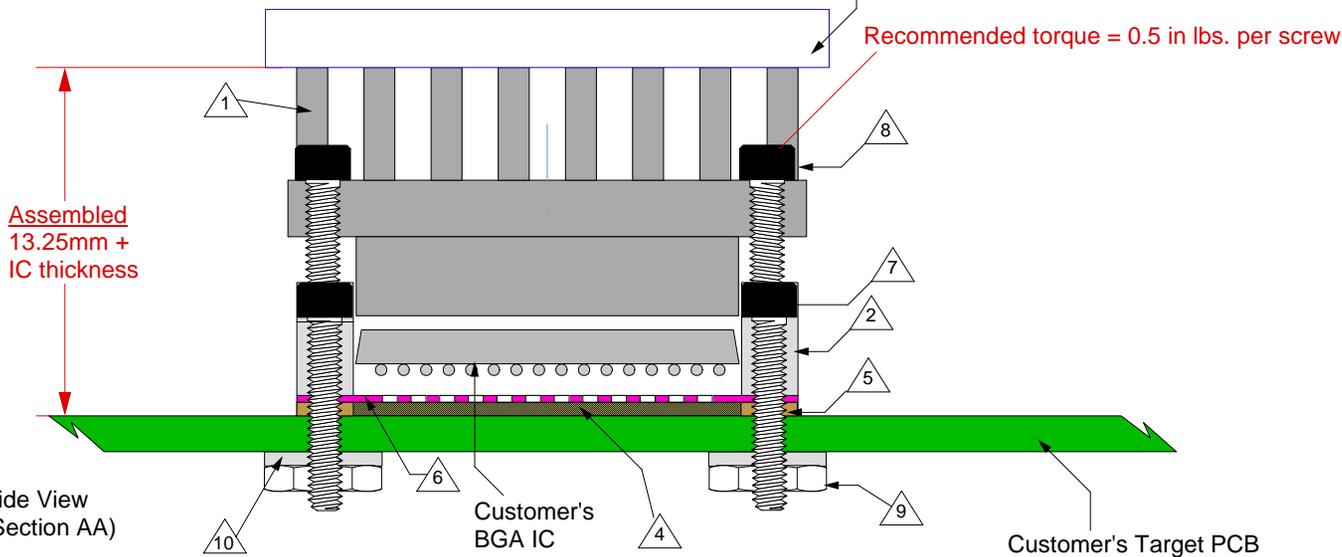
Top View



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



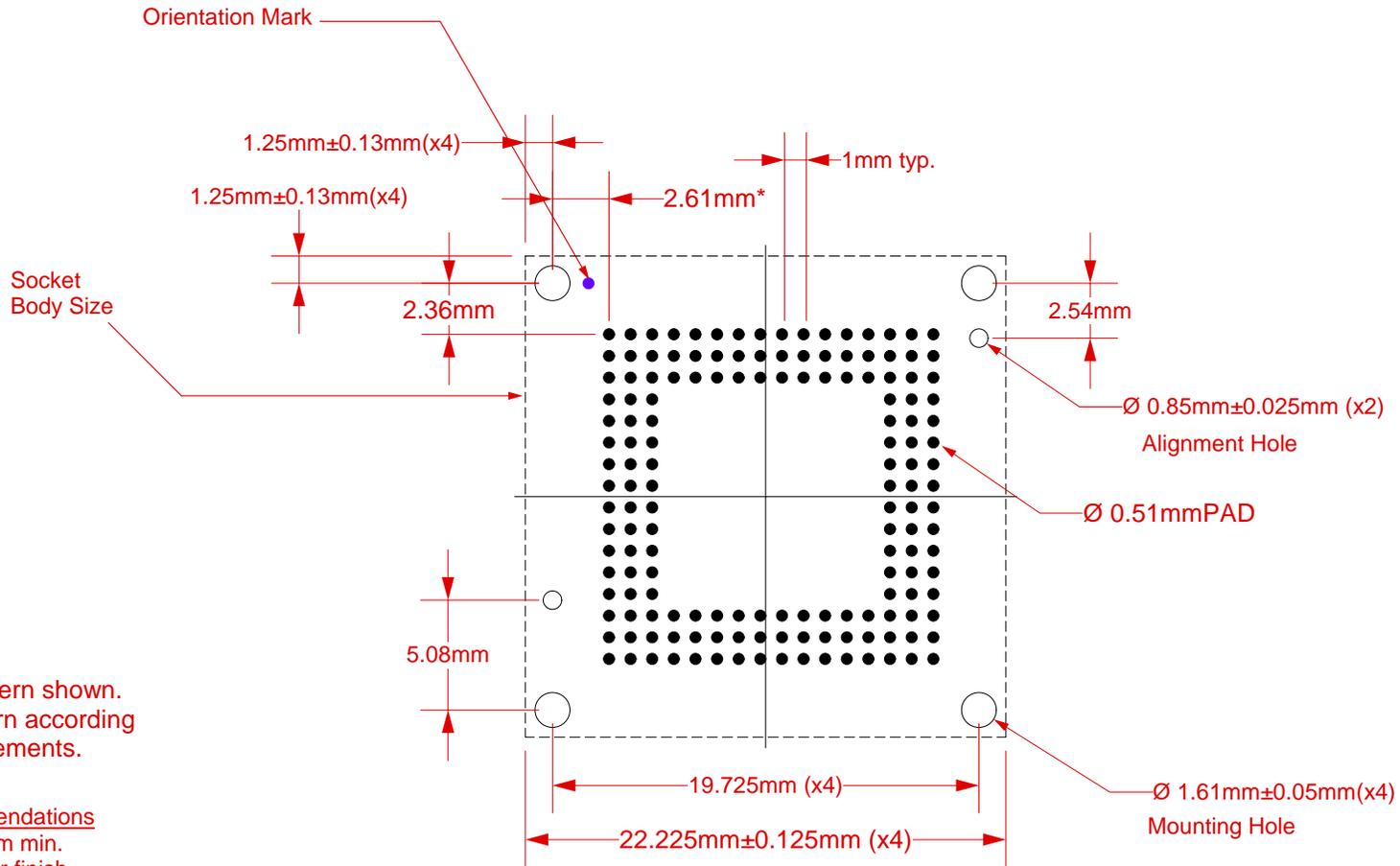
- 1 Heat sink lid: Black anodized Aluminum. Thickness = 2.5mm, Fins = 5mm, comp plate = 3.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Fan: 25x25x10mm, 5 V, 3.5 cfm. Thickness = 2.5mm.
- 4 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 5 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 6 Ball Guide: Kapton polyimide.
- 7 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- 8 Socket lid screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 4.76mm long.
- 9 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 10 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

	SG-BGA-8002 Drawing	Status: Released	Scale: -	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 3/16/07	
		File: SG-BGA-8002Dwg.mcd	Modified:	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

Target PCB Recommendations

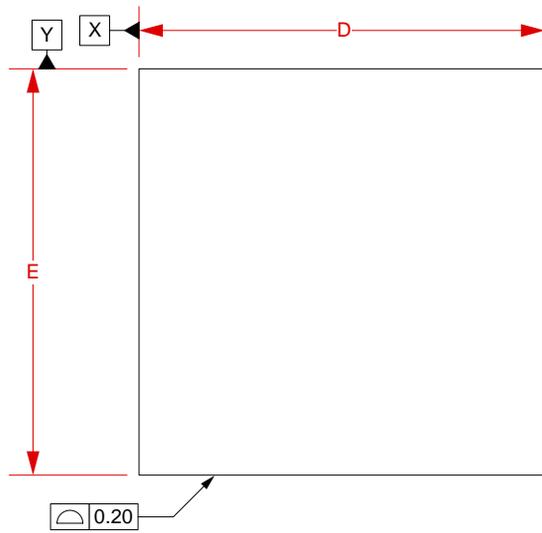
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

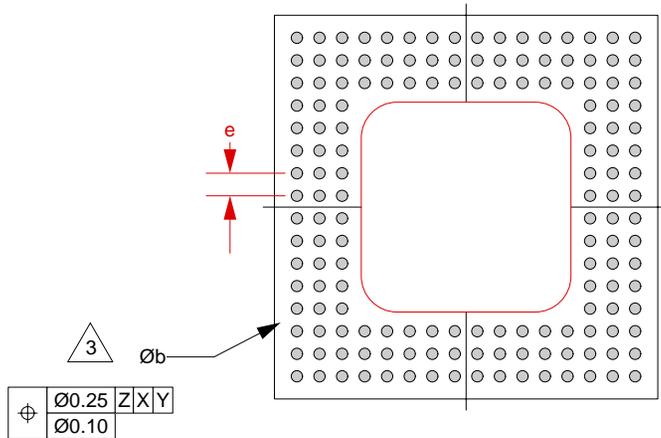
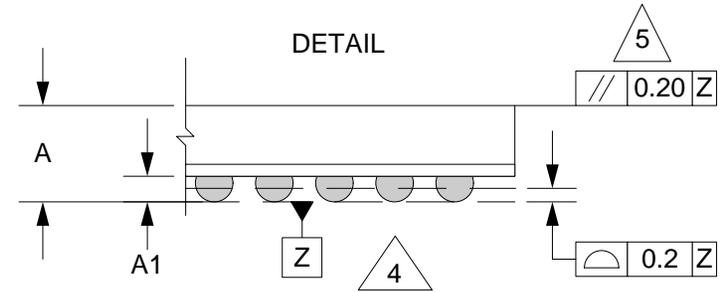
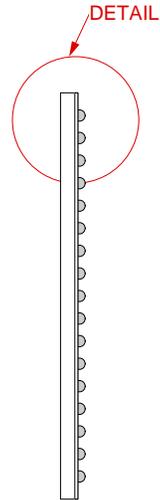
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

	SG-BGA-8002 Drawing	Status: Released	Scale: 3:1	Rev: A
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		File: SG-BGA-8002Dwg.mcd	Modified:	

TOP VIEW



SIDE VIEW



BOTTOM VIEW

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.7
A1	0.3	0.5
b		0.6
D	17.00 BSC	
E	17.00 BSC	
e	1.0 BSC	

Array 16x16

	SG-BGA-8002 Drawing	Status: Released	Scale: -	Rev: A
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		File: SG-BGA-8002 Dwg.mcd	Modified:	